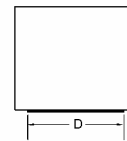
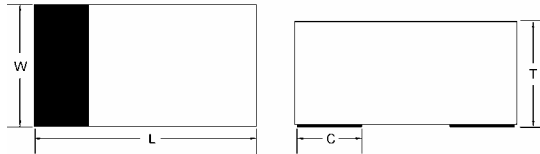
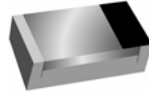


TSS0340L

0.03Amp Surface Mount Schottky Barrier Diode

1005



Features

- ✧ Designed for mounting on small surface
- ✧ Extremely thin/leadless package
- ✧ Low capacitance
- ✧ Low forward voltage drop
- ✧ High temperature soldering:
260°C/10 seconds at terminals
- ✧ Chip version in 1005

Mechanical Data

- ✧ Case: 1005 Standard package, molded plastic
- ✧ Terminals: Gold plated, solderable per MIL-STD-750, method 2026.
- ✧ Polarity: Indicated by cathode band
- ✧ Mounting position: Any
- ✧ Package code: RW
- ✧ Weight: 0.006 gram (approximately)

ITEM	1005
L	0.102(2.60)
	0.095(2.40)
W	0.051(1.30)
	0.043(1.10)
T	0.035(0.90)
	0.027(0.70)
C	0.020(0.50)
	Typical
D	0.040(1.00)
	Typical

Dimensions in inches and (millimeters)

Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise specified

Type Number	Symbol	1005	Units
Repetitive Peak Reverse Voltage	V_{RRM}	45	V
DC Reverse Voltage	V_R	40	V
Average Forward Current	I_O	30	mA
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}	500	mA
Power Dissipation	P_d	200	mW
Forward Voltage $I_F=1.0\text{mA}$	V_F	0.37	V
Reverse Leakage Current $V_R=30\text{V}$ $V_R=40\text{V}$	I_R	0.5	μA
		1.0	μA
Typical capacitance between terminals $V_R=1\text{V}$, $f=1.0\text{MHz}$ reverse voltage	C_J	1.5	pF
Junction Temperature	T_J	-40 to + 125	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 to + 125	$^\circ\text{C}$

RATINGS AND CHARACTERISTIC CURVES (TSS0340L)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

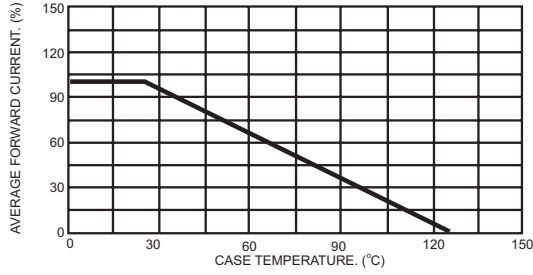


FIG.2- TYPICAL REVERSE CHARACTERISTICS

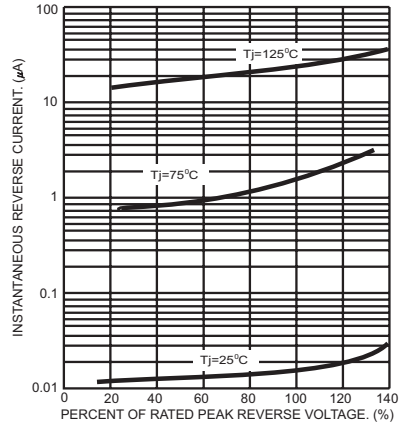


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

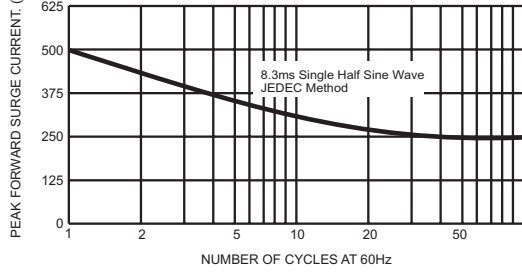


FIG.5- FORWARD CHARACTERISTICS CURVE

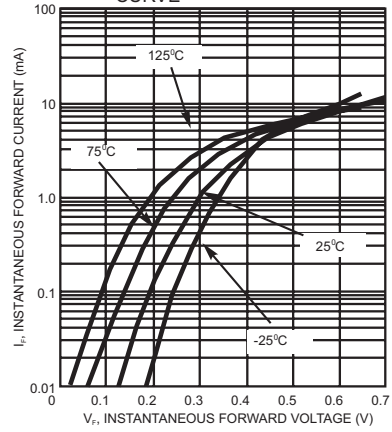


FIG.4- TYPICAL JUNCTION CAPACITANCE

